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(12) **United States Design Patent**
Lee et al.

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- (54) **LED CHIP**
- (75) Inventors: **Chia-En Lee**, Chia Yi (TW); **Te-Ling Hsia**, New Taipei (TW); **Wen-Fei Fong**, Hsin Chu (TW)
- (73) Assignee: **Lextar Electronics Corp.**, Hsinchu (TW)
- (*) Notice: This patent is subject to a terminal disclaimer.
- (**) Term: **14 Years**
- (21) Appl. No.: **29/406,557**
- (22) Filed: **Nov. 16, 2011**

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- (30) **Foreign Application Priority Data**
- May 24, 2011 (TW) 100302531
- (51) **LOC (9) Cl.** **13-03**
- (52) **U.S. Cl.**
- USPC **D13/180**
- (58) **Field of Classification Search** D13/180;
- D26/1, 2; 257/79, 80, 81, 88, 89, 95, 98,
- 257/99, 100, E33.058; 313/483, 498, 500;
- 362/555, 800
- See application file for complete search history.

Primary Examiner — Selina Sikder
(74) *Attorney, Agent, or Firm* — Schmeiser, Olsen & Watts LLP

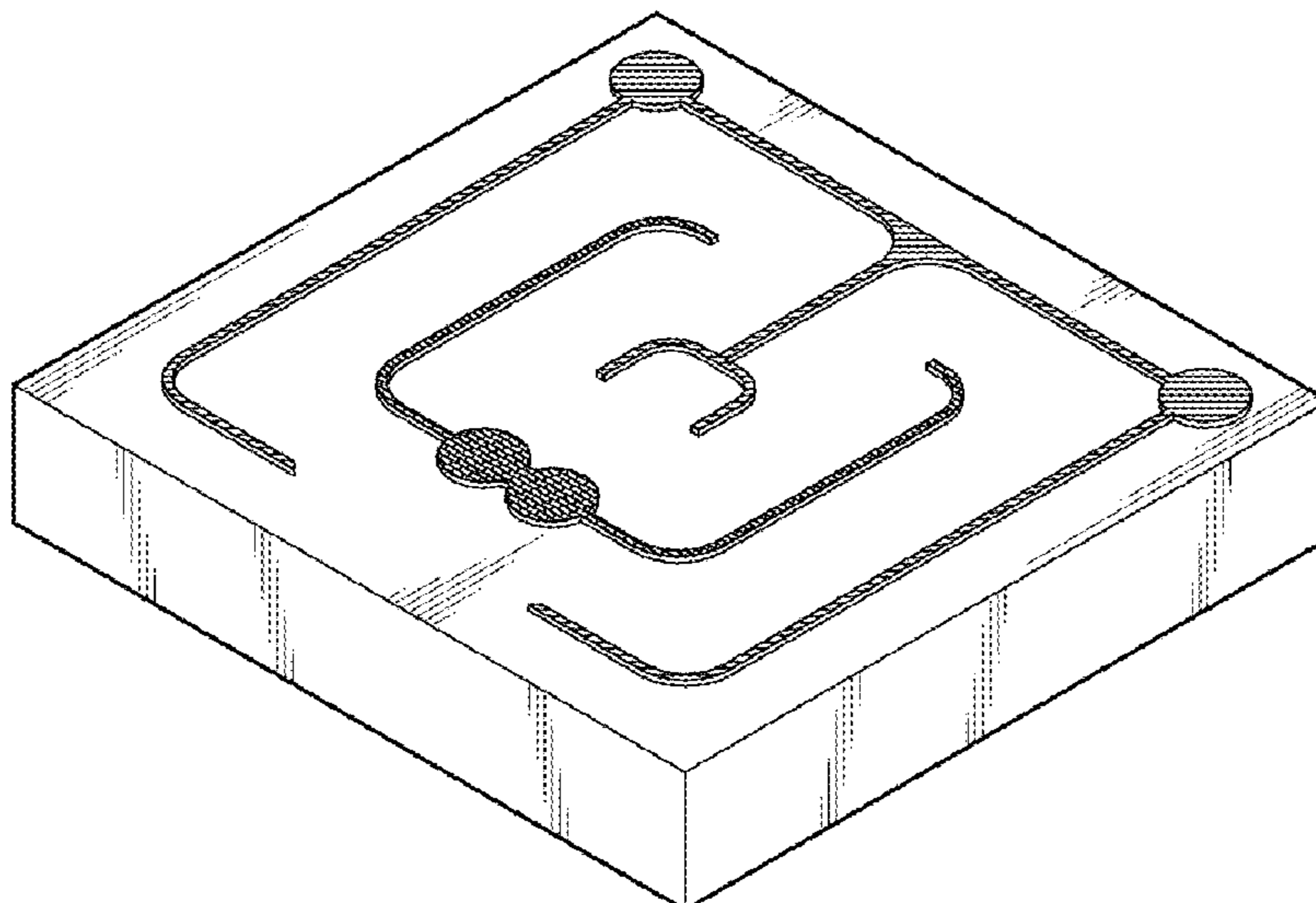
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(57) **CLAIM**
The ornamental design for LED chip, as shown and described.

DESCRIPTION

FIG. 1 is a front perspective view of LED chip showing the new design;
FIG. 2 is a front elevational view thereof;
FIG. 3 is a rear elevational view thereof;
FIG. 4 is a left side elevational view thereof;
FIG. 5 is a right side elevational view thereof;
FIG. 6 is a top plan view thereof; and,
FIG. 7 is a bottom plan view thereof.

1 Claim, 7 Drawing Sheets



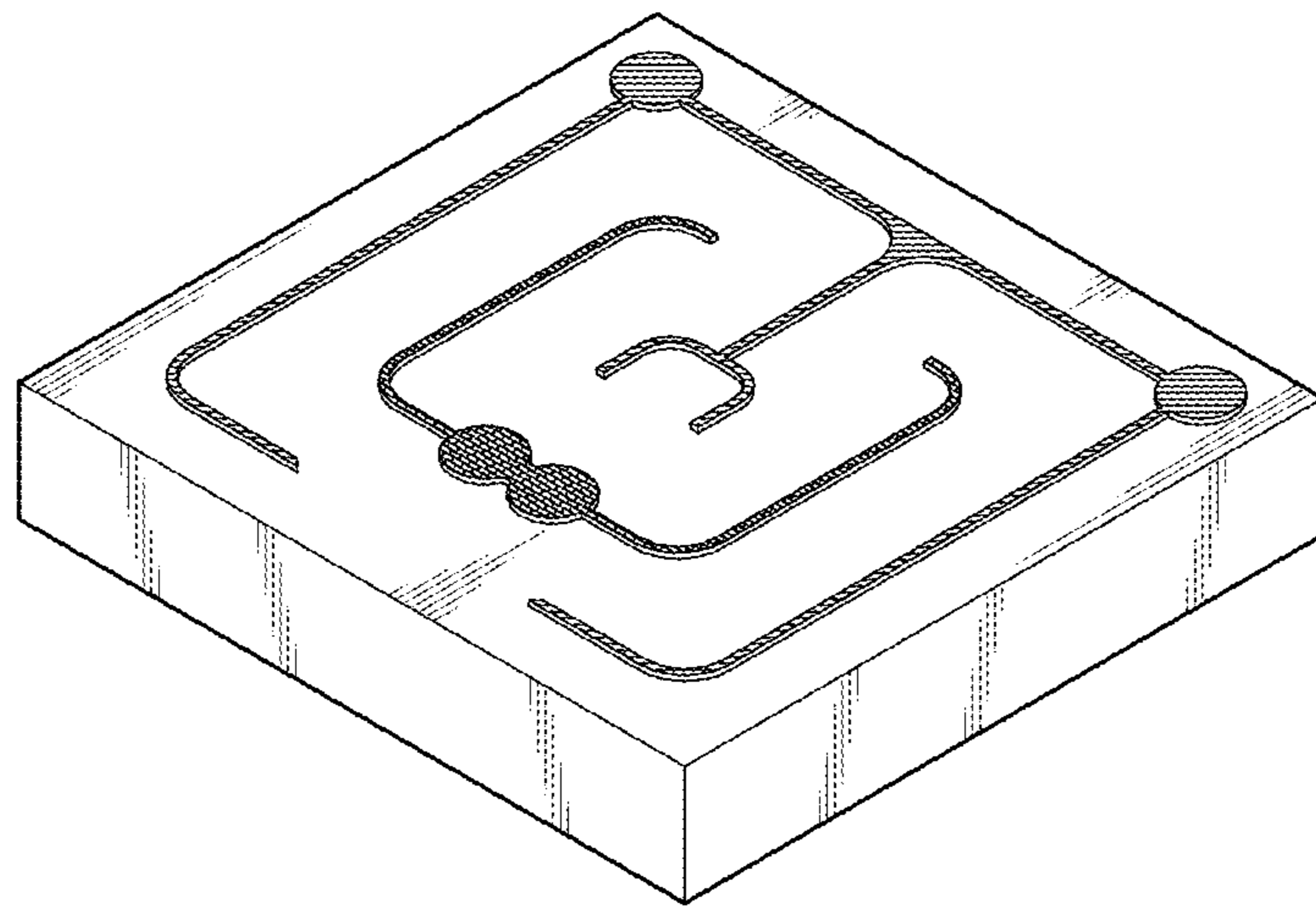


FIG. 1



FIG.2



FIG.3



FIG.4

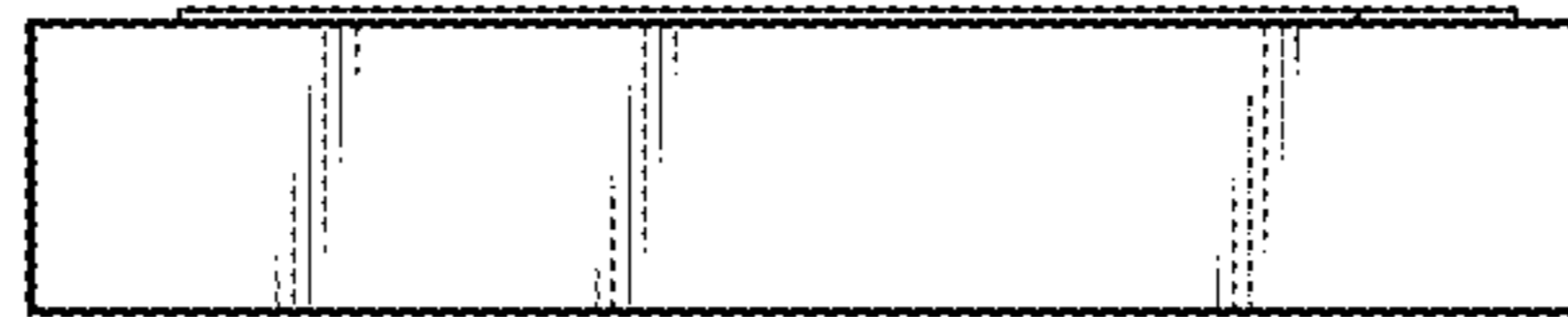


FIG.5

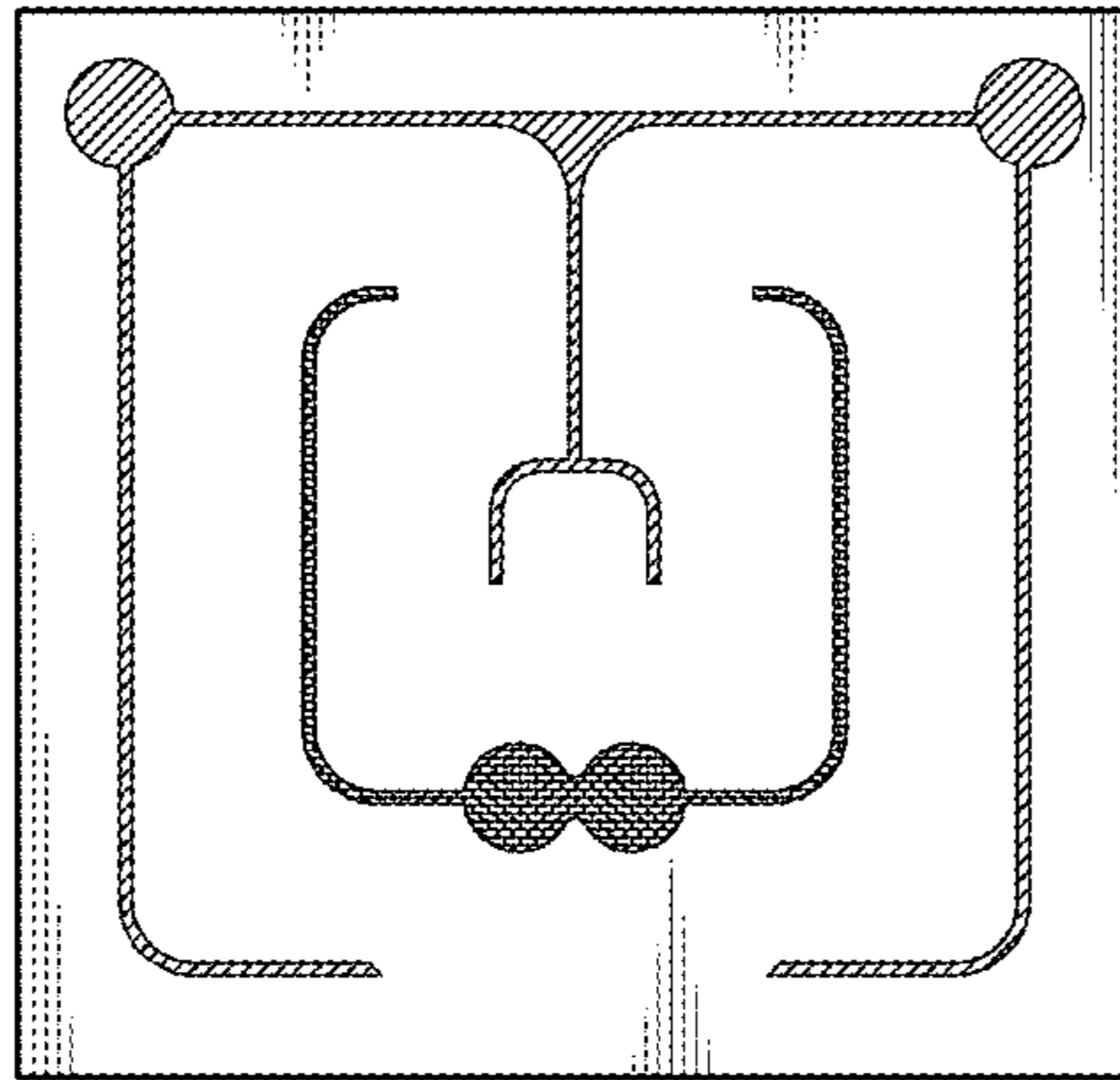


FIG.6

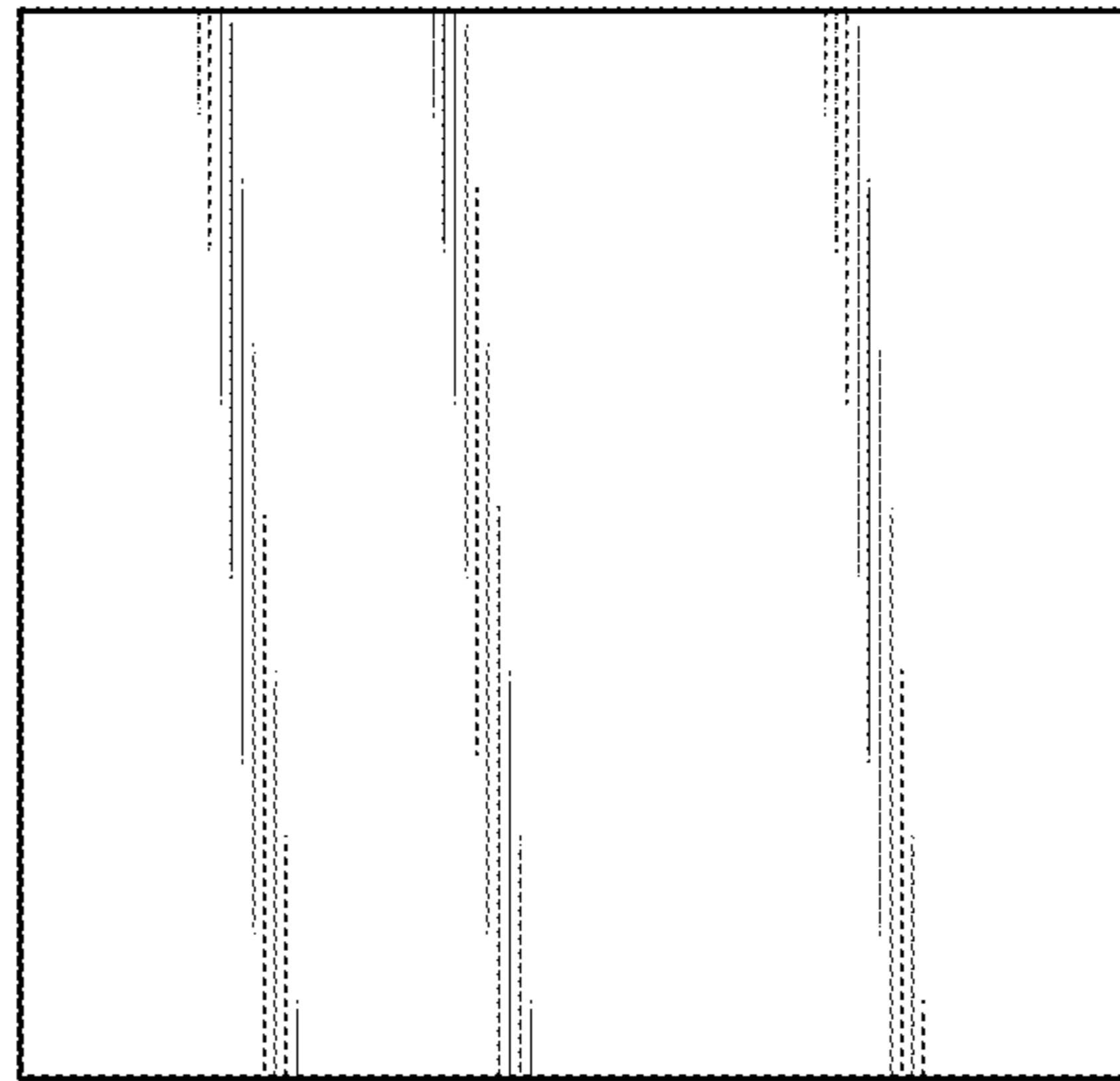


FIG.7